



Semiconductor Device Type: (J5A) 004 VDFN 2.0x2.5mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	5.24 (mg) Total	Mold Compound	% of Total Weight	
Silica, fused	60676-86-0	Mold Compound	38.331	4.715	383,310	5.24	Silica, fused	60676-86-0	90.00
Epoxy Resin	Trade Secret	Mold Compound	2.066	0.254	20,656		Epoxy Resin	Trade Secret	4.85
Phenolic Resin	Trade Secret	Mold Compound	2.066	0.254	20,656		Phenolic Resin	Trade Secret	4.85
Carbon Black	1333-86-4	Mold Compound	0.128	0.016	1,278		Carbon Black	1333-86-4	0.30
Copper	7440-50-8	Lead Frame	46.032	5.662	460,318		Total		100.00
Iron	7439-89-6	Lead Frame	1.110	0.137	11,101	5.81 (mg) Total		Lead Frame	% of Total Weight
Zinc	7440-66-6	Lead Frame	0.059	0.007	591	5.81		Copper	7440-50-8
Phosphorous	7723-14-0	Lead Frame	0.039	0.005	390			Iron	7439-89-6
Silica Fused	60676-86-0	Die Attach	1.104	0.136	11,044			Zinc	7440-66-6
Epoxy Resin	120206-26-0	Die Attach	0.327	0.040	3,268			Phosphorous	7723-14-0
Poly(Bisphenol A-co-epichlorohydrin)	25068-38-6	Die Attach	0.249	0.031	2,488			Total	
Silicon	7440-21-3	Chip (Die)	6.610	0.813	66,100	0.21 (mg) Total		Die Attach	% of Total Weight
Gold	7440-57-5	Wire Bond	0.570	0.070	5,700	0.21		Silica Fused	60676-86-0
Nickel	7440-02-0	Plating on external leads (pins)	1.179	0.145	11,790			Epoxy Resin	120206-26-0
Palladium	7440-05-3	Plating on external leads (pins)	0.066	0.008	655			Poly(Bisphenol A-co-epichlorohydrin)	25068-38-6
Gold	7440-57-5	Plating on external leads (pins)	0.066	0.008	655			Total	
TOTALS:			100.000	12.300	1,000,000	0.81 Total (mg)		Chip (Die)	% of Total Weight
0.0123 g Total Mass						0.81		Doped Silicon	7440-21-3
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)								Total	
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.								100.00	
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.						0.07 (mg) Total		Wire Bond	% of Total Weight
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/						0.07		Gold	7440-57-5
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.								Total	
Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.								100.00	
Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgement, and invoices.						0.16 (mg) Total		Plating on external leads (pins)	% of Total Weight
Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.						0.16		Nickel	7440-02-0
Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table								Palladium	7440-05-3
								Gold	7440-57-5
								Total	
								100.00	

12.30

100.00